

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM358812

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT OF THE ENTIRE INTEREST AND THE GOODWILL		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
The Bergquist Company		03/31/2015	CORPORATION: MINNESOTA
RECEIVING PARTY DATA			
Name:	Henkel AG & Co. KGaA		
Street Address:	Henkelstrasse 67		
City:	Duesseldorf		
State/Country:	GERMANY		
Postal Code:	40587		
Entity Type:	partnership limited by shares: GERMANY		
PROPERTY NUMBERS Total: 21			
Property Type	Number	Word Mark	
Registration Number:	2428046	BERGQUIST	
Registration Number:	2352281	BERGQUIST HI-FLOW	
Registration Number:	2180959	BOND-PLY	
Registration Number:	3067144	CPU PAD	
Registration Number:	2286975	GAP PAD	
Registration Number:	3153830	GAP PAD VO ULTRA SOFT	
Registration Number:	4404864	HEATSEAL	
Registration Number:	2955730	HIGHROAD	
Registration Number:	1778307	IMS	
Registration Number:	3186316	ISOEDGE	
Registration Number:	4358423	LIQUI-FORM	
Serial Number:	85242483	LIQUI-PAD	
Registration Number:	3024103	LIQUI-BOND	
Registration Number:	2918708	Q-PAD	
Registration Number:	1609077	SIL-PAD	
Registration Number:	1022666	SIL-PADS	
Registration Number:	1842374	SOFTFACE	
Serial Number:	85837501	STABILUX	
Registration Number:	2844581	T-CLAD	

CH \$540.00 2428046

Property Type	Number	Word Mark
Registration Number:	1622499	THERMAL CLAD
Registration Number:	2025055	TRIPLESEAL

CORRESPONDENCE DATA

Fax Number: 8605715028

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 8605712661

Email: amy.wergeles@henkel.com, lizette.sayah@henkel.com

Correspondent Name: Amy Span Wergeles, Henkel Corporation

Address Line 1: One Henkel Way

Address Line 2: Law Department - Trademarks

Address Line 4: Rocky Hill, CONNECTICUT 06067

ATTORNEY DOCKET NUMBER:	BERGQUIST RECORDATION
NAME OF SUBMITTER:	Amy Span Wergeles
SIGNATURE:	//Amy Span Wergeles//
DATE SIGNED:	10/15/2015

Total Attachments: 10

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ASSIGNMENT OF TRADEMARKS

This ASSIGNMENT OF TRADEMARKS ("Agreement"), dated as of 3/1/2015 (the "Effective Date") is from **The Bergquist Company**, a Minnesota, USA, corporation located in Chanhassen, Minnesota, USA ("Assignor") to **Henkel AG & Co. KGaA**, a German partnership limited by shares located in Düsseldorf, Germany ("Assignee").

WHEREAS, Assignor is the owner of all right, title and interest in and to the trademarks and trademark registrations and applications described on Schedule A (the "Trademarks") attached hereto; and

WHEREAS, pursuant to a Stock Purchase Agreement dated September 11, 2014 (the "Stock Purchase Agreement"); Assignor was acquired by Assignee; and

WHEREAS, in accordance with the Stock Purchase Agreement, Assignor desires to transfer the Trademarks to Assignee.

NOW, THEREFORE, for good and valuable consideration, the sufficiency of which is hereby acknowledged:

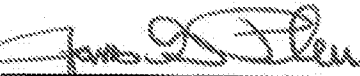
1. Assignment. Assignor hereby assigns and transfers to Assignee, and the Assignee agrees to purchase and acquire from the Assignor, all of the Assignor's right, title and interest in and to the Trademarks, together with any goodwill, if any, symbolized by the Trademarks, including without limitation, the right to any registrations thereof, the right to prosecute any applications therefor, the right to have any registrations issue in the name of the Assignee, the right to apply for and obtain any renewal of any registrations thereof, the right to sue for past and future infringement and the right to the goodwill of the business symbolized thereby.
2. Further Assurances. Assignor will execute any and all additional documents that may be reasonably necessary for Assignee to perfect the transfer of rights set forth herein.
3. Binding Provisions. This Agreement is binding upon, and inures to the benefit of, the parties hereto and their respective heirs, executors, legal representatives, successors, and permitted assigns.
4. Governing Law. All questions concerning the construction, validity and interpretation of this Agreement and the performance of the obligations imposed by this Agreement shall be governed by the law of Germany.

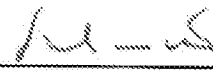
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IN WITNESS WHEREOF, the parties hereto have executed and delivered this Assignment of Trademarks as of the Effective Date:

THE BERGQUIST COMPANY

HENKEL AG&Co. KGaA

By: 
James G. Plewacki
Chief Financial Officer

By: 
ppa. Dr. Michael J. Schmitt
Proxy

By: 
Rick Samuelson
Market Development Manager

By: 
ppa. Joachim Renner
Proxy

SCHEDULE A

Trademark	Goods/Services	Country	Filing Date/ Reg. Date	Serial No./ Reg. No.	Status
BERGQUIST®	For insulating heat sink mounts for electronic devices; silicone coated electrical insulative film for use in commercial and industrial installations, sold in the form of sheets and special shapes; multifunction electronic membrane switches; mounting pads for semiconductor devices; heat conductive mounting pads for semiconductor devices; insulatory coating of plastic resin for use on semiconductors for use in manufacturing electronic equipment; mounting substrates for electronic components; fiberglass reinforcement substrates for use in commercial and industrial thermal management installations; thermally conductive, epoxy impregnated glass cloth for electrical insulation; electrical membrane switches; and electrically insulative, thermally conductive mounting pad for electronic devices.	United States	2/13/2001	2,428,046	Renewal due 02/13/2021
		Australia	5/22/2006	1080925	Renewal due 10/14/2015
		Canada	3/4/2008	TMA708872	Renewal due 03/04/2023
		China Int'l Class 9	9/21/2008	4949867	Renewal due 9/20/2018
		China Int'l Class 17	6/28/2009	5188253	Renewal due 6/27/2019
		China (in Chinese) Int'l Class 9	11/21/2009	5526984	Renewal due 11/20/2019
		China (in Chinese) Int'l Class 17	1/7/2010	6017913	Renewal due 1/6/2020
		Europe	8/25/2006	4685517	Renewal due 10/14/2015

BERGQUIST® Continued		Japan	1/26/2007	5021332	Renewal due 1/26/2017
		Taiwan	8/1/2006	1220707	Renewal due 7/31/2016
		S. Korea	8/20/2013	989,779	Renewal due 8/20/2023
BERGQUIST HI-FLOW®	Films for mounting semiconductors on chassis surfaces	United States	5/23/2000	2,352,281	Renewal due 5/23/2020
		Taiwan	1/15/1999	835,846	Renewal due 1/15/2019
		Japan	10/19/2001	4,515,825	Renewal due 10/19/2021
BOND-PLY®	For electrically insulative, thermally conductive mounting pad for electronic devices.	United States	8/11/1998	2,180,959	Renewal due 8/11/2018
CPU PAD®	For electrically insulative, thermally conductive interface for electronic devices.	United States	3/14/2006	3,067,144	Renewal due 3/14/2016
GAP PAD®	For electrically insulative, thermally conductive interface for electronic devices.	United States	10/19/1999	2,286,975	Renewal due 10/19/2019
		Japan	3/17/2000	4369183	Renewal due 3/17/2020
		Taiwan	8/16/2007	1274852	Renewal due 8/15/2017
		European Community	4/3/2009	6192421	Renewal due 8/13/2017
		S. Korea	5/2/2013	966,890	Renewal due: 5/2/2023
GAP PAD VO ULTRA SOFT®	For electronically insulative, thermally conductive interface for mounting electronic devices onto chassis, heat sinks or printed circuitry boards.	United States	10/10/2006	3,153,830	Abandoned per R. Samuelson 10/5/12

HEATSEAL®	Electronic membrane switches.	United States	9/17/2013	4,404,864	Renewal due 9/17/2019
HI-FLOW®	Thermal Interface materials, namely, thermally conductive films and coatings for use as heat transfer interfaces between electronic components and thermal dissipation members.	European Community	6/17/2008	6192645	Renewal due 8/13/2017
HIGHROAD®	For heat management components for incorporation in electronic assemblies and printed circuit boards, namely, insulating heat sink mounts fitted for electronic devices; silicone coated electrical insulative film fitted for use in commercial and industrial installations, sold in the form of sheets and special shapes; multifunction electronic membrane switches; mounting pad fitted for semiconductor devices; insulatory coatings of plastic resin sold as a component of semiconductors for use in manufacturing electronic equipment; mounting substrates for incorporation in electronic components; electrical membrane switches; electrical insulative, thermally conductive mounting pads fitted for electronic components; and computer touchscreen monitors.	United States	5/24/2005	2,955,730	Renewal due 05/24/2015
		Australia	2/7/2005	974086	Renewal due 10/13/2023
		Canada	4/19/2006	TMA662760	Renewal due 04/19/2021
		China	10/7/2005	3786551	Renewal due 10/06/2015
		Europe	3/15/2005	3405024	Renewal due 10/14/2023
		Japan	4/22/2005	4859889	Renewal due 04/22/2015
		Taiwan	10/16/2004	1123171	Renewal due 10/15/2024

IMS®	For mounting substrates for electronic components. Estonia will not be renewed in light of 2008-3692 Lithuania will not be renewed in light of 2008-3692 Latvia will not be renewed in light of 2008-3692	United States	6/22/1993	1,778,307	Renewal due: 6/22/2023
		Estonia	4/17/1996	19192	Abandoned in favor of 2008-3692
		Hong Kong	7/8/1991	02280/93	Renewal due 07/08/2026
		Lithuania	2/24/1998	25493	Abandoned in favor of 2008-3692
		Latvia	10/20/1996	M-34124	Abandoned in favor of 2008-3692
		Russian Federation	5/17/1996	142,019	Renewal due 10/15/2023
		Taiwan	12/16/1998	86054666	Renewal due 06/16/2018
	European Community	10/25/2012	6785711	Renewal due 3/27/2018	
ISOEDGE®	For heat plates for use with electronic devices.	United States	12/19/2006	3,186,316	Renewal due 12/19/2016
LIQUI-FORM®	Electrically insulative, thermally conductive interfaces in the nature of liquid formable materials for mounting electronic devices onto chassis, heat skins, or printed circuitry boards.	United States	6/25/2013	4,358,423	Renewal due: 6/25/2019
LIQUI-PAD	Electrically insulative, thermally conductive interfaces for mounting electronic devices onto chassis, heat skins, or printed circuitry boards.	United States	2/15/2011	85/242,483	Allowed - Statement of use due 4/30/2015

LIQUI-BOND®	For adhesives for general industrial use with thermal transfer devices in automotive electronics, telecommunications equipment, computer and computer peripherals, and heat generating semi-conductors.	United States	12/6/2005	3,024,103	Renewal due 12/06/2015
Q-PAD®	For fiberglass reinforcement substrates for use in commercial and industrial thermal management installations; and silicone coated electrical insulative film for use in commercial and industrial thermal management installations. Estonia will not be renewed in light of 2011-4719 Great Britain will not be renewed in light of 2011-4719 Latvia will not be renewed in light of 2011-4719 Lithuania will not be renewed in light of 2011-4719	United States	1/18/2005	2,918,708	Renewal due 1/18/2025
		European Community	12/14/2011	9,838,608	Renewal due 3/24/2021
		Estonia	4/17/1996	19,191	Abandoned in favor of 2011-4719
		Great Britain	3/19/1991	1,458,733	Abandoned in favor of 2011-4719
		Hong Kong	4/11/1991	B1902/1997	Renewal due 04/11/2022
		Japan	10/31/1994	2,697,841	Renewal due 10/31/2024
		Latvia	10/27/1993 10/20/1996	M-938416 M-34123	Abandoned in favor of 2011-4719
		Lithuania	11/12/1993 08/18/1997	ZP - 13830 24385	Abandoned in favor of 2011-4719
		South Korea	6/16/1992	240,971	Renewal due 06/16/2022
		Russian Federation	2/15/1996	138,040	Renewal due 10/20/2023
Taiwan	11/16/1991	538,857	Renewal due 5/16/2021		

SIL-PAD®	Mounting pads for semiconductor devices. Estonia will not be renewed in light of 2008-3644 Latvia will not be renewed in light of 2008-3644 Lithuania will not be renewed in light of 2008-3644	United States	8/7/1990	No.1609077	Renewal due 08/07/2020
		European Community	1/16/2009	No.6651699	Renewal due 2/7/2018
		Estonia	4/17/1996	19,189	Abandoned in favor of 2008-3644
		Hong Kong	4/11/1991	B-3101/95	Renewal due 04/11/2022
		Japan	5/31/1994	2,670,995	Renewal due 05/31/2024
		Latvia	10/20/1996	M-34122	Abandoned in favor of 2008-3644
		Lithuania	8/18/1997	24,384	Abandoned in favor of 2008-3644
		Russian Federation	5/10/1995	125,829	Renewal due 10/20/2023
		Singapore	5/16/1991	T91/04951G	Renewal due 5/16/2021
		South Korea	6/16/1992	240,970	Renewal due 06/16/2022
SIL-PADS® Registration to go abandoned per Bergquist 1/6/2009	For insulating heat sink mount for electronic devices NOTE: NO foreign renewals to be filed.	United States	10/14/1975	No.1022666	Renewal due 10/14/2015
		France	7/10/1986	No.1363023	Renewal due 07/10/2016
		Great Britain	11/16/1984	1,230,369	Renewal due 11/16/2015
		Switzerland	9/22/1976	283,972	Renewal due 07/22/2016
		West Germany	4/29/1977	957,407	Renewal due 07/31/2016

SOFTFACE®	For interfacing for mounting of encapsulated semiconductor devices onto chassis. Great Britain will not be renewed in light of 2011-4720	United States	6/28/1994	1,842,374	Renewal due 06/28/2024
		European Community	8/30/2011	9,837,791	Renewal due 3/24/2021
		Great Britain	4/15/1991	1,461,244	Abandoned in favor of 2011-4720
		Hong Kong	5/1/1991	No. 5384/93	Renewal due 05/01/2026
		Taiwan	11/16/1991	538,858	Renewal due 10/15/2021
StabiLUX	Chemical coatings used in the manufacture of printed circuit boards, namely, soder mask.	United States	1/31/2013	85/837,501	Allowed. Statement of use due 3/10/2015
T-CLAD®	For electrical power cords, leads, and connections for North American and international adaptation.	United States	5/25/2004	2,844,581	Renewal due 5/25/2024
		Australia	7/4/2005	978,147	Renewal due 11/12/2023
		Canada	6/28/2005	TMA643223	Renewal due 06/28/2020
		China	8/7/2005	3,805,233	Renewal due 08/06/2015
		Europe	8/8/2005	3,537,081	Renewal due 11/12/2023
		Japan	7/9/2004	4,785,273	Renewal due 07/09/2024
		Taiwan	12/1/2004	1,128,983	Renewal due 11/30/2024

THERMAL CLAD®	For heat conductive mounting pads for semiconductor devices. Estonia will not be renewed in light of 2011-4721 Latvia will not be renewed in light of 2011-4721 Lithuania will not be renewed in light of 2011-4721	United States	11/13/1990	1,622,499	Renewal due 11/13/2020
		European Community	Reg. 9837956	1/2/2012	Renewal due 3/24/2021
		Estonia	4/17/1996	19190	Abandoned in favor of 2011-4721
		Hong Kong	9/28/1994	B-1850/97	Renewal due 09/28/2015
		Japan	11/30/1993	2,599,484	Renewal due 11/30/2023
		Latvia	10/20/1996	M-34121	Abandoned in favor of 2011-4721
		Lithuania	2/27/1997	24386	Abandoned in favor of 2011-4721
		Russian Federation	6/16/1995	128,348	Renewal due 10/20/2023
		South Korea	16/1992	240,972	Renewal due 06/16/2022
		Taiwan	11/16/1991	538,860	Renewal due 05/16/2021
		Ukraine	4/30/1998	9,663	Renewal due 10/22/2023
TRIPLESEAL®	For electrical membrane switches.	United States	12/24/1996	2,025,055	Renewal due 12/24/2016